SN54HC73, SN74HC73 DUAL J-K FLIP-FLOPS WITH CLEAR

D2684, DECEMBER 1982-REVISED SEPTEMBER 1987

- Package Options Include Plastic "Small Outline" Packages and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

description

These devices contain two independent J-K negative-edge-triggered flip-flops. A low level at the Clear input resets the outputs regardless of the other inputs. When Clear is inactive (high), data at the J and K inputs meeting the setup time requirements are transferred to the outputs on the negative-going edge of the clock pulse. Following the hold time interval, data at the J and K inputs may be changed without affecting the levels at the outputs. These flip-flops can also perform as toggle flip-flops by tying J and K high.

The SN54HC73 is characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to $125\,^{\circ}\text{C}$. The SN74HC73 is characterized for operation from $-40\,^{\circ}\text{C}$ to $85\,^{\circ}\text{C}$.

FUNCTION TABLE (EACH FLIP-FLOP)

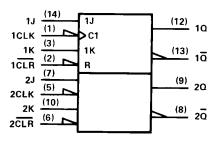
INPUTS				OUT	PUTS
CLR	CLK	J	K	Q	ā
L	X	X	Х	Н	L
Н	ţ	L	L	σ_0	\overline{a}_0
Н	ţ	Н	L	н	L
Н	ţ	L	Н	L	н
Н	ţ	Н	Н	TOGGLE	
н	Н	X	X	<u>a</u> o	₫0

SN54HC73 . . . J PACKAGE SN74HC73 . . . D OR N PACKAGE (TOP VIEW)

1CLK	1	∪14∏ 1J
1CLR	2	13 🗍 1 🖸
1K [3	12 🗍 1 Q
Vcc □	4	11 GND
2CLK	5	10 🔲 2K
2CLR	6	9 🔲 20.
2J 🗌	7	8 <u>2</u> 2

For functionally and electrically identical parts in chip carrier, see SN54HC107.

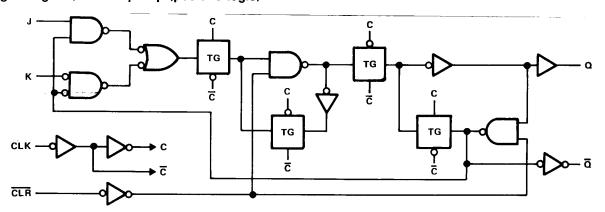
logic symbol†



†This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, and N packages.

logic diagram, each flip-flop (positive logic)



PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



absolute maximum ratings over operating free-air temperature range †

Supply voltage, VCC
Input clamp current, IIK (VI < 0 or VI > VCC)
Output clamp current, IOK (VO < 0 or VO > VCC ±20 mA
Continuous output current, IO (VO = 0 to VCC)
Continuous current through VCC or GND pins
Lead temperature 1,6 mm (1/16 in) from case for 60 s: J package
Lead temperature 1,6 mm (1/16 in) from case for 10 s: D or N package
Storage temperature range65 °C to 150 °C

[†]Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54HC73			s	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	CIVIT
V _{CC} Supply voltage		2	5	6	2	5	6	٧
	$V_{CC} = 2 V$	1.5			1.5			
V _{IH} High-level input voltage	$V_{CC} = 4.5 V$	3.15			3.15			V
	$V_{CC} = 6 V$	4.2			4.2			
-	V _{CC} = 2 V	0		0.3	0		0.3	
V _{IL} Low-level input voltage	$V_{CC} = 4.5 V$	0		0.9	0		0.9	V
·	V _{CC} = 6 V	0		1.2	0		1.2	
V _I Input voltage		0		Vcc	0		၁ <mark></mark>	٧
VO Output voltage		0		٧cc	0		VCC	V
	V _{CC} = 2 V	0		1000	0		1000	
t _t Input transition (rise and fall) times	$V_{CC} = 4.5 V$	0		500	0		500	ns
	V _{CC} = 6 V	0		400	0		400	
TA Operating free-air temperature		- 55		125	-40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS		TA = 25°C			SN54HC73		SN74HC73		UNIT
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
	-	2 V	1.9	1.998		1.9		1.9		
	$V_I = V_{IH}$ or V_{IL} , $I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
V _{OH}		6 V	5.9	5.999		5.9		5.9		V
	$V_I = V_{IH} \text{ or } V_{IL}, I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.30		3.7		3.84		
	$V_I = V_{IH}$ or V_{IL} , $I_{OH} = -5.2$ mA	6 V	5.48	5.80		5.2		5.34		
		2 V		0.002	0.1		0.1		0.1	
	$V_I = V_{IH}$ or V_{IL} , $I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1		0.1	
V _{OL}		6 V		0.001	0.1		0.1		0.1	V
to a real object	V _I = V _{IH} or V _{IL} , I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
	$V_I = V_{IH}$ or V_{IL} , $I_{OL} = 5.2$ mA	6 V		0.15	0.26		0.4		0.33	
l ₁	V _I = V _{CC} or 0	6 V		±0.1	±100	±	1000	=	± 1000	nA
!cc	$V_I = V_{CC}$ or 0, $I_O = 0$	6 V			4		80		40	μΑ
C _i		2 to 6 V		3	10		10		10	ρF

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			V	TA =	25°C	SN54	HC73	SN74	HC73	UNIT
			vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	0	6	0	4.2	0	5	
fclock	Clock frequency		4.5 V	0	31	0	21	0	25	MHz
0.00.			6 V	0	36	0	25	0	29	
			2 V	80	<u>. </u>	120		100		
		CLK high or low	4.5 V	16		24		20		ns
			6 V	14		20		17		
tw	Pulse duration	CLR low	2 V	80		120		100		
			4.5 V	16		24		20		ns
			6 V	14		20		17		
-	0.1.1.0.0.0.0.0.0.0.0.0.0.0.0.0.0.0.0.0	· ·	2 V	100		150		125		
t _{su}	Setup time, CLR inactive		4.5 V	25		35		30		ns
0	or data before CLK+	or data before CLKI		20		30		25		
				0		0		0		
th	Hold time, data after CLK	(1	4.5 V	0		0		0		ns
			6 V	0		0		0		

switching characteristics over recommended operating free-air temperature range (unless otherwise noted), $C_L = 50 pF$ (see Note 1)

242445752	FROM	то		T _A = 25°C			SN54HC73		SN74HC73		UNIT
PARAMETER	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	6	11		4.2		5		
f _{max}			4.5 V	31	54		21		25		MHz
			6 V	36	64		25		29		
			2 V		78	155		250		194	
tPHL	CLR	٥	4.5 V	}	16	31		47		39	ns
			6 V		13	26		40		32	
			2 V		78	155		250		194	
tPLH	CLR	₫	4.5 V		16	31		47		39	ns
			6 V		13	26		40		32	
			2 V		63	126		185		160	
t _{pd}	CLK	Q or Q	4.5 V		13	25		37		32	ns
P -			6 V		11	21		32		27	
			2 V		38	75		110		95	
t _t		Any	4.5 V		8	15		22		19	ns
-			6 V		6	13	<u> </u>	19		16	

Cpd	Power dissipation capacitance per flip-flop	No load, T _A = 25 °C	30 pF typ

NOTE 1: Load circuit and voltage waveforms are shown in Section 1.

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